

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} = 0V, V _{DS} = 600V T _j = 25°C			350	μA
		V _{GS} = 0V, V _{DS} = 600V T _j = 125°C			600	
R _{DS(on)}	Drain – Source on Resistance	V _{GS} = 10V, I _D = 47.5A			24	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = 5mA	2.1	3	3.9	V
I _{GSS}	Gate – Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0V			200	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C _{iss}	Input Capacitance	V _{GS} = 0V ; V _{DS} = 25V		14.4		nF
C _{oss}	Output Capacitance	f = 1MHz		17		
Q _g	Total gate Charge	V _{GS} = 10V V _{Bus} = 300V I _D = 95A		300		nC
Q _{gs}	Gate – Source Charge			68		
Q _{gd}	Gate – Drain Charge			102		
T _{d(on)}	Turn-on Delay Time	Inductive Switching (125°C) V _{GS} = 10V V _{Bus} = 400V I _D = 95A R _G = 2.5Ω		21		ns
T _r	Rise Time			30		
T _{d(off)}	Turn-off Delay Time			100		
T _f	Fall Time			45		
E _{on}	Turn-on Switching Energy	Inductive switching @ 25°C V _{GS} = 10V ; V _{Bus} = 400V I _D = 95A ; R _G = 2.5Ω		1350		μJ
E _{off}	Turn-off Switching Energy			1040		
E _{on}	Turn-on Switching Energy	Inductive switching @ 125°C V _{GS} = 10V ; V _{Bus} = 400V I _D = 95A ; R _G = 2.5Ω		2200		μJ
E _{off}	Turn-off Switching Energy			1270		

Chopper diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V _{R RM}	Maximum Peak Repetitive Reverse Voltage		600			V
I _{RM}	Maximum Reverse Leakage Current	V _R = 600V	T _j = 25°C		100	μA
			T _j = 125°C		500	
I _F	DC Forward Current	T _c = 80°C		100		A
V _F	Diode Forward Voltage	I _F = 100A		1.6	2	V
		I _F = 200A		2		
		I _F = 100A T _j = 125°C		1.3		
t _{rr}	Reverse Recovery Time	I _F = 100A V _R = 400V di/dt = 200A/μs	T _j = 25°C	160		ns
			T _j = 125°C	220		
Q _{rr}	Reverse Recovery Charge	I _F = 100A V _R = 400V di/dt = 200A/μs	T _j = 25°C	290		nC
			T _j = 125°C	1530		

Thermal and package characteristics

Symbol	Characteristic	Min	Typ	Max	Unit	
R _{thJC}	Junction to Case Thermal Resistance	Transistor		0.27	°C/W	
		Diode		0.55		
V _{ISOL}	RMS Isolation Voltage, any terminal to case t = 1 min, 50/60Hz	4000			V	
T _J	Operating junction temperature range	-40		150	°C	
T _{STG}	Storage Temperature Range	-40		125		
T _C	Operating Case Temperature	-40		100		
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package Weight			80		g

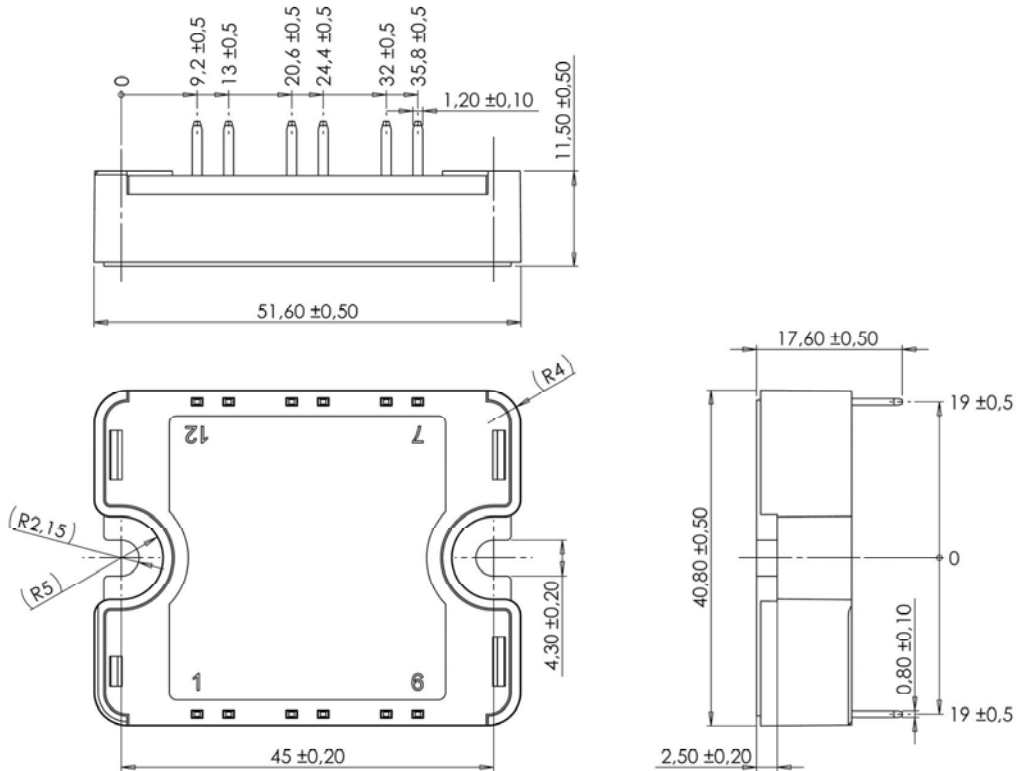
Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C		50		kΩ
B _{25/85}	T ₂₅ = 298.15 K		3952		K

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

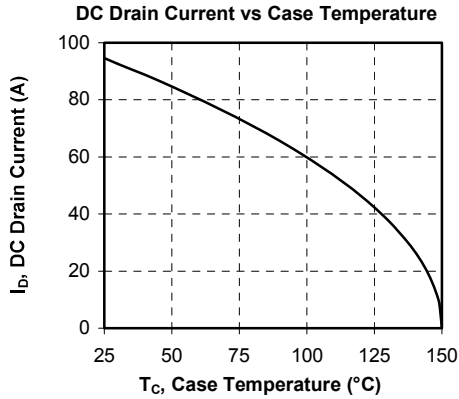
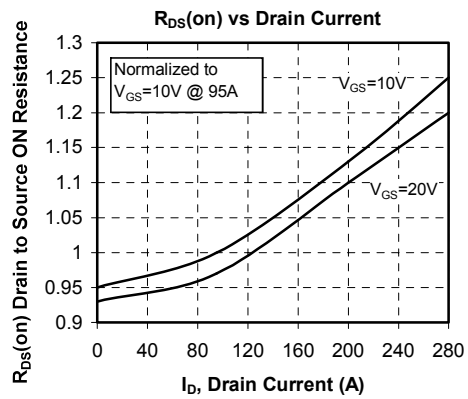
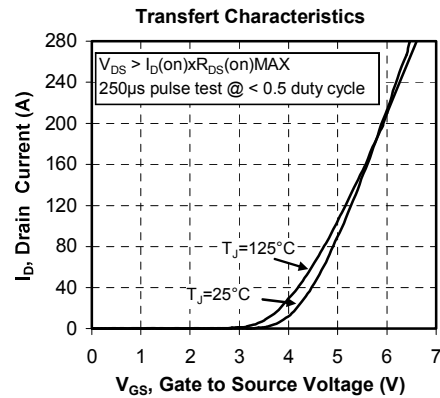
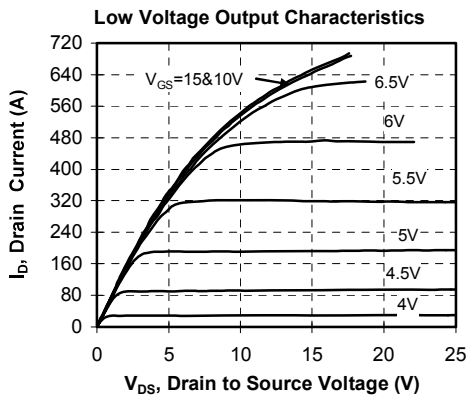
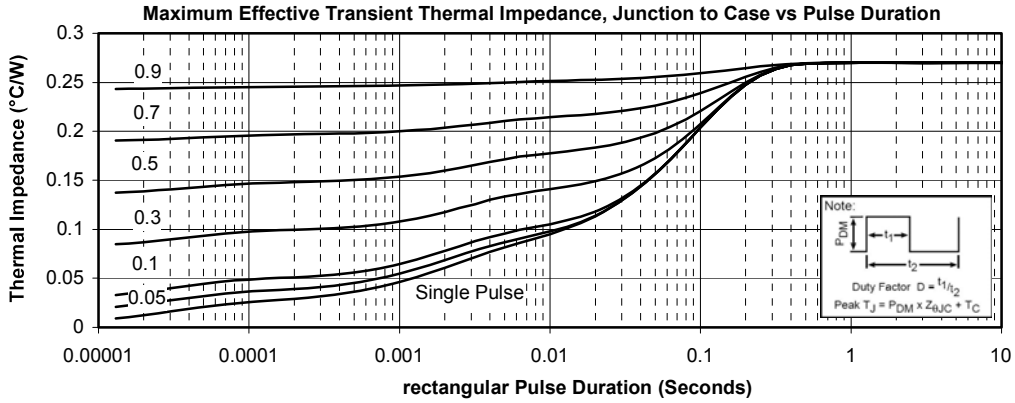
T: Thermistor temperature
 R_T: Thermistor value at T

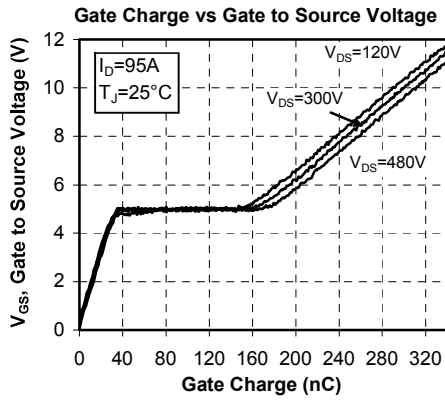
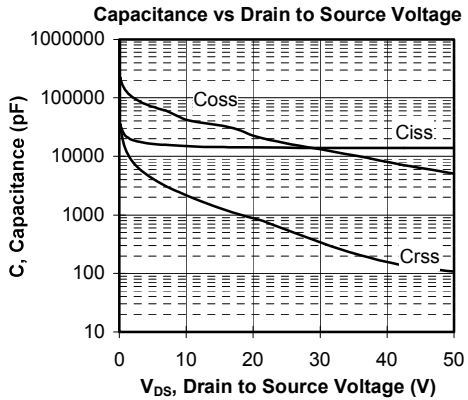
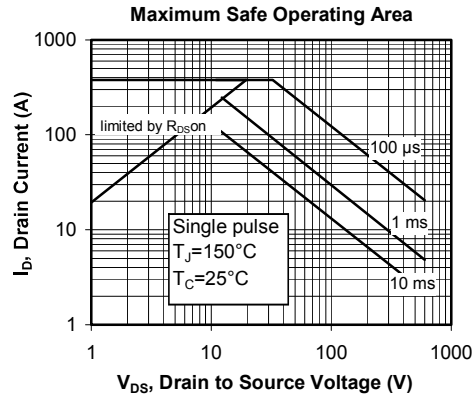
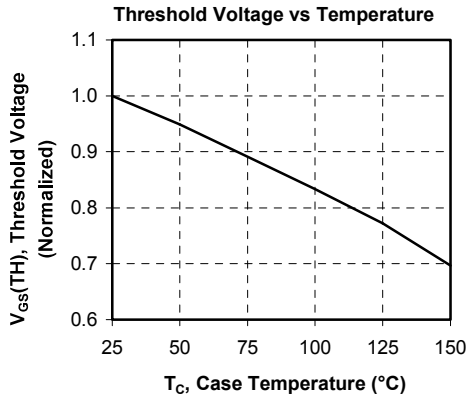
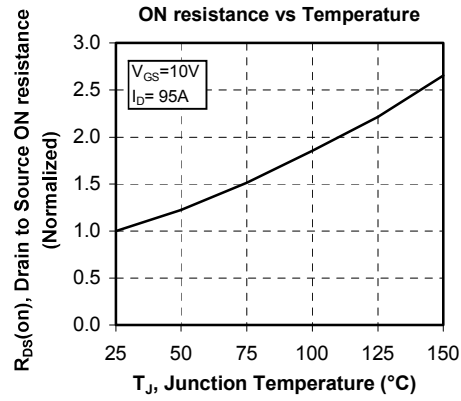
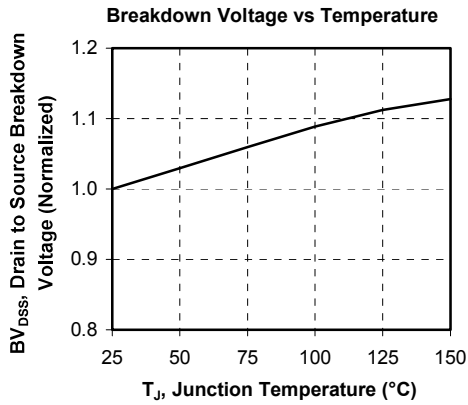
SP1 Package outline (dimensions in mm)

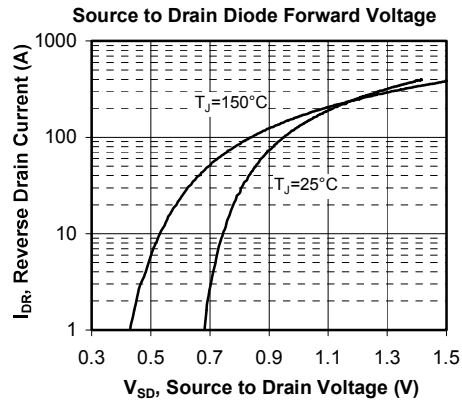
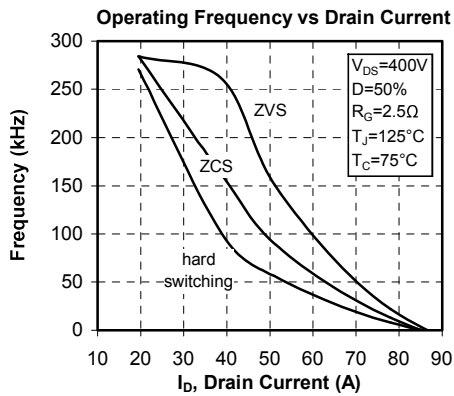
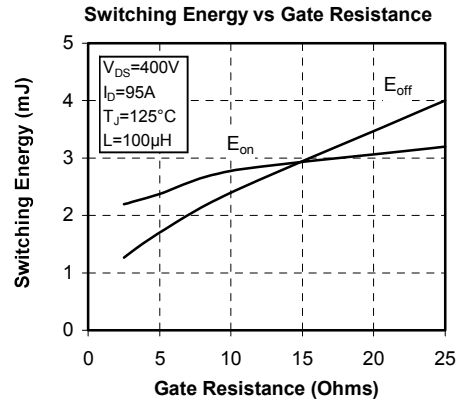
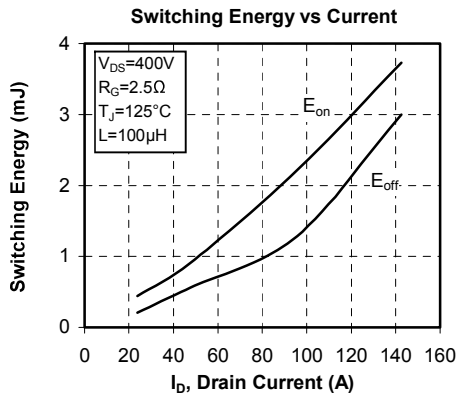
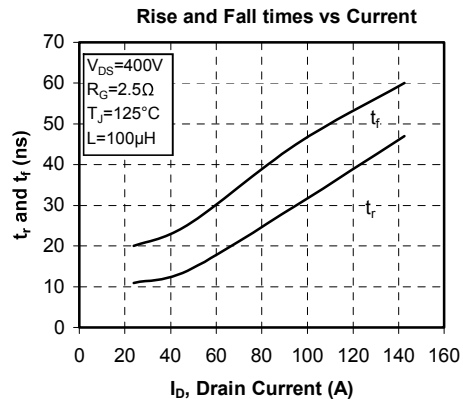
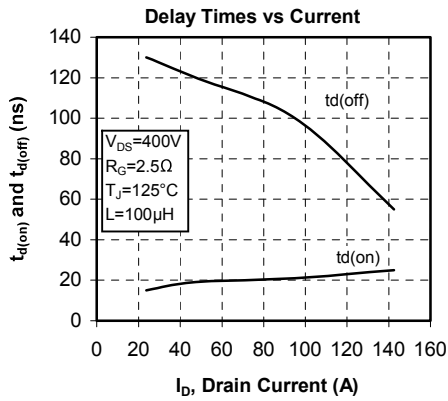


See application note 1904 - Mounting Instructions for SP1 Power Modules on www.microsemi.com

Typical Performance Curve







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